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TFT | CHARACTER | UWVD | FSC | SEGMENT | CUSTOM | REPLACEMENT

TFT Display Module

Part Number E15RA-FW255-N

Overview:

- 1.5-inch TFT (33.32x36.06mm)
- 240x240 pixels
- 8/9/16/18-bit MCU
- 3-line/4-line Serial
- 3/4SPI+16/18 RGB

- Transmissive/Normally Black
- White LED Backlight
- 255 NITS
- Controller: ST7789V
- RoHS Compliant



Description

This is a color active matrix TFT (Thin Film Transistor) LCD (Liquid Crystal Display) that uses amorphous silicon TFT as a switching device. This model is composed of a transmissive type TFT-LCD Panel, driver circuit, and a backlight unit. The resolution of the 1.5" TFT-LCD contains 240(RGB)x240 pixels and can display up to 262k colors.

TFT Features

Low Input Voltage: 3.3V Display Colors: 65k/262k colors Interfaces: 3/4-wire serial 8/9/16/18-bit MCU 3/4-wire SPI+16/18-bit RGB

General Information Items	Specification Main Panel	Unit	Note
TFT Display area (AA)	27.72(H) x 27.72(V) (2.0 inch)	mm	-
Driver Element	TFT active matrix	-	-
Display Colors	65k/262k	colors	-
Number of pixels	240(RGB)x240	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel Pitch	0.1155(H)x0.1155(V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	ST7789V	-	-
Interface	3/4-serial 8/9/16/18-bit MCU 3/4-SPI+16/18-bit RGB	-	-
Display mode	Transmissive/ Normally Black	-	-
Operating temperature	-20~+70	°C	-
Storage temperature	-30~+80	°C	-

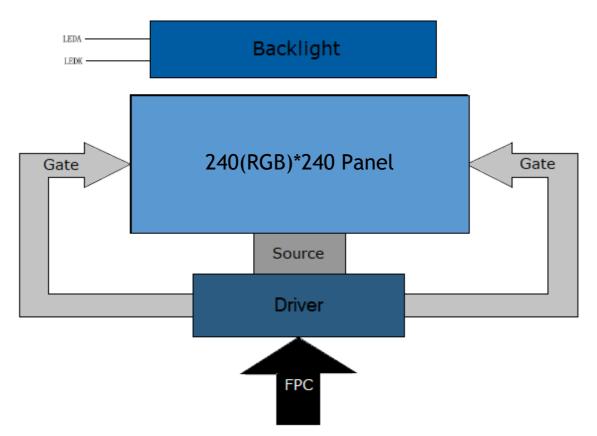
Mechanical Information

Item		Min	Тур.	Max	Unit	Note
	Horizontal (H)		33.32		mm	-
Module	Vertical (V)		36.06		mm	-
Size	Depth (D)		2.25		mm	-
	Weight				g	

1. Outline Dimensions В Α С D F G E ReV. Revision content description Date V0 FIRST 2019.08.28 33,32±0.15 BL 2, 25±0. 2 LCM 29,52±0.2 POL NO. Pin Name 1 LEDA 27, 72 LCDAA NC 3 LEDK 16.66 — 4 NC 5 GND 6 GND 8 VCC 9 IOVCC 2 2 SDO 10 11 DB17 36 12 DB16 8 N 1.5' DB15 .06±0. Pull tape 3 12 ± 0 240 (W) x240 (H) DB14 15 DB13 LCDAA Friee 15 16 DB12 DB11 B P DB10 19 DB09 20 DB08 20 DB07 22 DB06 3 23 DB05 24 DB04 25 DB03 26 DB02 27 DB01 DB0 28 8 29 DIN(SDA) 30 PCLK 31 DE 32 HSYNC - 0.13 FPC Tape 33 VSYNC 34 RD 35 WR(SPI-RS) 36 RS(SPI-SCL) 37 CS អ្ន CONTACT SIDE PI ?? ~ 15 38 RESET 39 MO 40 M1 41 M2 Detail:A 42 NC 43 NC 9,76±0.5 - 27.92±0.2-44 NC 45 NC 5 5 SET for IM 36 Fin is : 7-1810,089-B17-DB10 22 0817-DB 0 NOTES: 13.8 ± 0.05 DRI THE SHEET IN 55 1. DISPLAY TYPE: 1.5" TFT-LCD, 65K/262K COLORS P0. 3*44=13. 2±0. 03 ||+||+||+|<mark>|+</mark>, 0.3 ± 0.07 2. DISPLAY MODE: NORMALLY BLACK A SCL (3. VIEWING DIRECTION: ALL 0.6±0.02 0.3 0.15 1. If not use PIN, fix to the GND , HOVCC $2_{\rm e} I_{\rm MC}^{\rm e}$ use RGB mode must select serial 4. LCM DRIVER IC: ST7789V (COG) ω 6 6 5. LCM Interface: MCU+RGB i finn 6. Touch Mode: Non 7. Touch Driver: Non ~~~ 8. Touch Interfac: Non FocusLCDs.com 0.2 0.1 0.3 9. Touch and LCM Bonding technology: Non LEDK • 🕅 R R • LEDA LCDs MADE SIMPLE* 10. VCC/VCI: 3.3V;IOVCC:1.8~3.3V CIRCUIT DIAGRAM 11. OPERATING TEMP: -20°C TO 70°C Detail A3 1 PARTS NO STORAGE TEMP: -30°C TO 80°C E15RA-FW255-N FH26-45S-0.3SHW 12. BACK LIGHT: LED WHITE, 3 LED, 20mA,9.9±0.3V TOLERANCE UNLESS . Drawn Unit X.X±0.3 13. Contrast Ratio: 14. LCM Brightness: cd/m2 OTHERWISE SPECIFIED X.XX±0.2 Checked mm 15. RoHS COMPLIANT. \rightarrow Approve Page Scale 1:1 А В С D Ε F G



2. Block Diagram





3.1	TFT	~	
NO.	Symbol	Description	1/0
1	LEDA	Anode pin of the backlight	Р
2	NC		
3	LEDK	Cathode pin of the backlight	Р
4	NC		
5	GND	Ground	Р
6	GND	Ground	Р
7	VCC	Supply voltage (3.3V)	Р
8	VCC	Supply voltage (3.3V)	Р
9	IOVCC	Supply voltage (1.65-3.3V)	Р
10	SDO	Supply voltage (1.65-3.3V)	0
11-28	DB17-DB0	18-bit parallel bi-directional data bus for MCU and RGB interface. Fix to GND when not used.	I/O
29	DIN(SDA)	When IM3: Low, SPI interface input/output pin. When IM3: High, SPI interface input pin. The data is latched on the rising edge of the SCL signal. If not used, fix to IOVCC or GND.	1/0
30	PCLK	Dot clock signal for RGB interface. Fix to IOVCC or GND when not used.	I
31	DE	Data enable signal for the RGB interface. Fix to IOVCC or GND when not used.	I
32	HSYNC	Line synchronizing signal for the RGB interface. Fix to IOVCC or GND when not used.	I
33	VSYNC	Frame synchronizing signal for the RGB interface. Fix to IOVCC or GND when not used.	1
34	RD	Read signal for the MCU interface. Reads data at the rising edge. Fix to IOVCC or GND when not used.	I
35	WR(SPI-RS)	Write signal for the MCU interface. Display data/command selection pin for the 4-wire serial interface. Second data line for the 2 data serial interface. Fix to IOVCC or GND when not used.	I
36	RS(SPI-SCL)	Data/command selection pin in the parallel interface. Serial clock for the serial interface. RS=1: display data, RS=0 command data. Fix to IOVCC or GND when not used.	I
37	CS	Chip select signal. Low enabled. Fix to IOVCC or GND when not used.	I
38	RESET	Reset signal of the device. Must be applied to properly initialize the chip.	I
39	IM0	MPU parallel interface and serial interface selection. If using RGB interface, you must	I
40	IM1	select the serial interface pins. Fix to IOVCC or GND when not used.	I
41	IM2		I
42	NC	-	
43	NC	-	
44	NC	-	
45	NC	-	
· Innut	O. Outnut P. P.		

3. Input Terminal Pin Assignment

I: Input, O: Output, P: Power



4. LCD Optical Characteristics

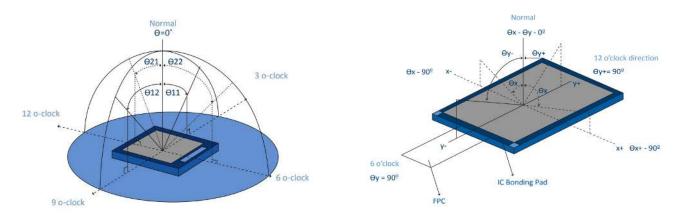
4.1 Optical Specifications

ltem		Symbol	Condition	Min	Тур.	Max	Unit	Note	
Color Gan	nut	S%			50		%	(3)	
Contrast R	atio	CR			800		%	(2)	
Response Time	Rising	TR+TF			30	40	ms	(4)	
Response nine	Falling				50	40	1115	(4)	
	\A/b:to	Wx	θ=0	0.249	0.289	0.329			
	White	Wy	Normal viewing	0.248	0.298	0.338			
	Red	Pod	R _X	anglo	0.543	0.583	0.623		
Color Filter		R _Y	angle	0.322	0.362	0.402		(5)(6)	
Chromaticity	Green	G _X		0.272	0.312	0.352		(5)(6)	
	Green	Gy		0.493	0.533	0.573			
	Blue	B _X		0.114	0.154	0.194			
	ыце	By		0.053	0.093	0.133			
		ΘL		60	80				
Viewing Angle	Hor.	ΘR	CR≥10	60	80		dograa	(1)(6)	
Viewing Angle		ΘΤ		60	80		degree	(1)(6)	
Ver.		ΘΒ		60	80				
Option View Di	rection			ALL				(1)	



Optical Specification Reference Notes:

(1) Definition of Viewing Angle: The viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3,9 o'clock direction and the vertical or 6,12 o'clock direction with respect to the optical axis which is normal to the LCD surface.



(2) Definition of Contrast Ratio (Cr): measured at the center point of panel. The contrast ratio (Cr) measured on a module, is the ratio between the luminance (Lw) in a full white area (R=G=B=1) and the luminance (Ld) in a dark area (R=G=B=0).

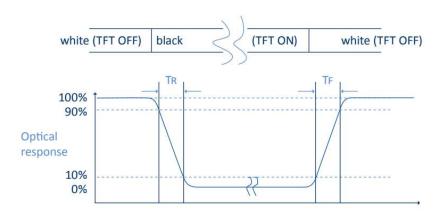
$$Cr = \frac{Lw}{Ld}$$

(3) Definition of transmittance (T%): The transmittance of the panel including the polarizers is measured with electrical driving. The equation for transmittance Tr is:

$$Tr = \frac{It}{Io} \times 100\%$$

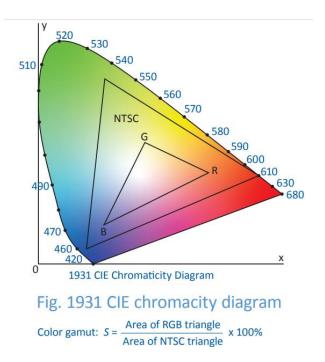
Io = the brightness of the light source. It = the brightness after panel transmission

(4) Definition of Response Time (Tr, Tf): The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.



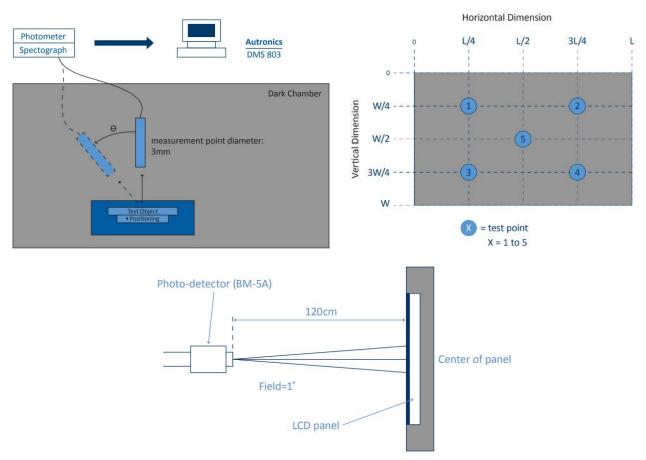


(5) Definition of Color Gamut: Measuring machine CFT-01. NTSC's Primaries: R(x,y,Y),G(x,y,Y), B(x,y,Y). FPM520 of Westar Display Technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.The color chromaticity shall be calculated from the spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.



(6) Definition of Optical Measurement Setup:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 20 minutes.





5. TFT Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 °C, VSS=0V)

Characteristics	Symbol	Min	Max	Unit
Digital Supply Voltage	VDD	-0.3	4.6	V
Digital Interface Supply Voltage	IOVCC	-0.3	4.6	V
Operating Temperature	ТОР	-20	+70	°C
Storage Temperature	TST	-30	+80	°C

NOTE: If the absolute maximum rating of the above parameters is exceeded, even momentarily, the quality of the product may be degraded. Absolute maximum ratings specify the values which the product may be physically damaged if exceeded. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min	Тур.	Max	Unit	Note
Digital Supply Voltage	VCC	2.4	3.3	3.6	V	
Digital Interface Supply Voltage	IOVCC	1.65	1.8	3.3	V	
Normal Mode Current Consumption	IDD		7		mA	
Level Input Voltage	VIH	0.7IOVCC		IOVCC	V	
Level input voltage	VIL	GND		0.3IOVCC	V	
Level Output Voltage	VOH	0.8IOVCC		IOVCC	V	
	VOL	GND		0.2IOVCC	V	



5.3 LED Backlight Characteristics

Item	Symbol	Min	Тур.	Max	Unit	Note
Forward Current	IF	15	20		mA	
Forward Voltage	VF		9.9		V	
LCM Luminance	LV	200	255		cd/m2	Note 3
LED lifetime	Hr	50000			hour	Note1 & 2
Uniformity	AVg	80			%	Note 3

The back-light system is edge-lighting type with 3 white LEDs.

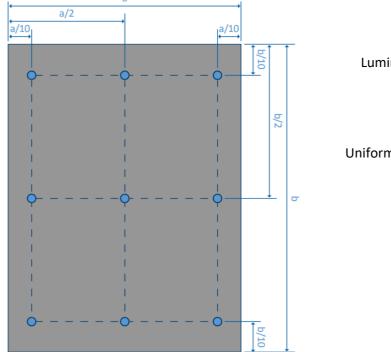
Note 1: LED lifetime (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25 ± 3 °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED lifetime" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=20mA. The LED lifetime could be decreased if operating IL is larger than 20mA. The constant current driving method is suggested.



Backlight LED Circuit

Note 3: Luminance Uniformity of these 9 points is defined as below:



Luminance = <u>(Total Luminance of 9 points)</u> 9

Uniformity =<u>minimum luminance in 9 points(1-9)</u> maximum luminance in 9 points(1-9)



6. AC Characteristic

6.1 Parallel RGB Interface Characteristics

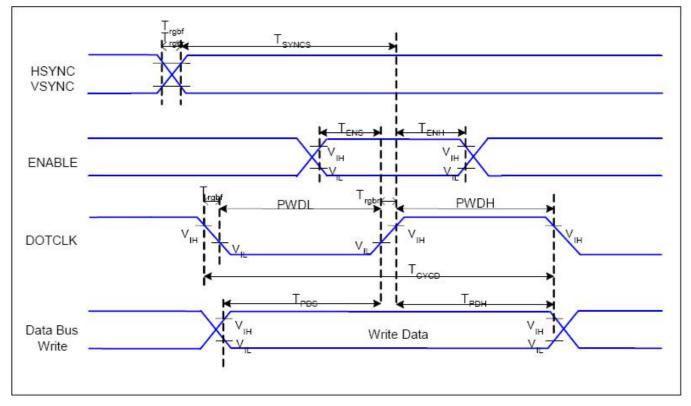
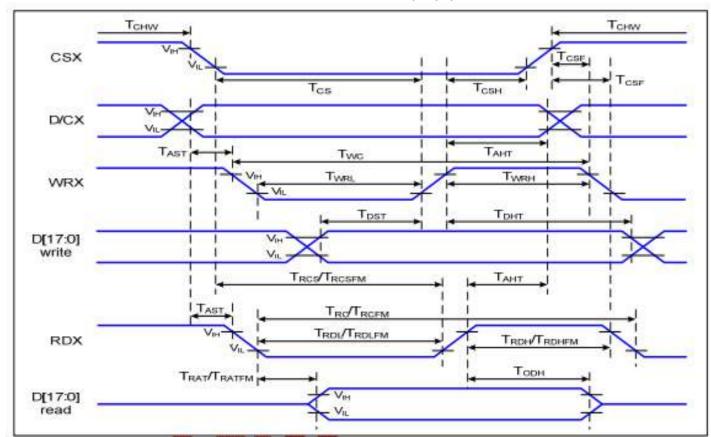


Figure 6.1: Parallel RGB Interface Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
HSYNC, VSYNC	T _{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
	T_{ENS}	Enable Setup Time	25	-	ns	
ENABLE	T _{ENH}	Enable Hold Time	25	-	ns	
	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
DOTCLK	T _{CYCD}	DOTCLK Cycle Time	120	-	ns	
	T _{RGHR} , T _{RGHF}	DOTCLK Rise/Fall Time	-	20	ns	
	T _{PDS}	PD Data Setup Time	50	-	ns	
DB	T _{PDH}	PD Data Hold Time	50	-	ns	

Table 6.1: Parallel RGB Interface Timing Characteristics





6.2 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

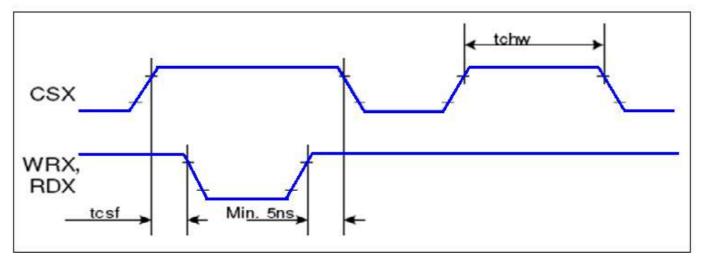
Figure 6.2: Parallel Interface Timing Characteristics (8080-Series MCU Interface)

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0	-	ns	
	T _{AHT}	Address hold time (Write/Read)	10	-	ns	-
CSX	T _{CHW}	Chip select "H" pulse width	0	-	ns	
	T _{CS}	Chip select setup time (Write)	15	-	ns	
	T _{RCS}	Chip select setup time (Read ID)	45	-	ns	
	T _{RCSFM}	Chip select setup time (Read FM)	355	-	ns	
	T_{CSF}	Chip select wait time (Write/Read)	10	-	ns	
	Т _{СSH}	Chip select hold time	10	-	ns	
WRX	T _{WC}	Write cycle	66	-	ns	
	T _{WRH}	Control pulse "H" duration	15	-	ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
RDX (ID)	T _{RC}	Read cycle (ID)	160	-	ns	
	T _{RDH}	Control pulse "H" duration (ID)	90	-	ns	
	T _{RDL}	Control pulse "L" duration	45	-	ns	
RDX (FM)	T _{RCFM}	Read cycle (FM)	450	-	ns	
	T _{RDHFM}	Control pulse "H" duration (FM)	90	-	ns	
	T _{RDLFM}	Control pulse "L" duration (FM)	355	-	ns	
D[17:0]	T _{DST}	Write data setup time	10	-	ns	
D[15:0],	T _{DHT}	Write data hold time	10	-	ns	For max CL=30pF
D[8:0],	T _{RAT}	Read access time (ID)	-	40	ns]
D[7:0]	T _{RATFM}	Read access time (FM)	-	340	ns	For min CL=8pF
	T _{ROD}	Output disable time	20	80	ns]

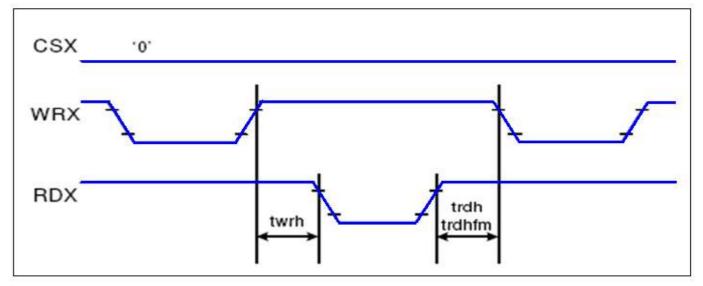
Table 6.2: 8080 Series MCU Parallel Timing Characteristics





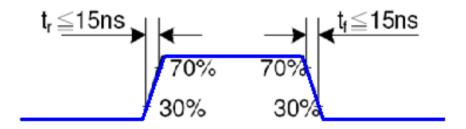


Note: Logic high and low levels are specified as 30% and 70% of IOVCC for input signals.

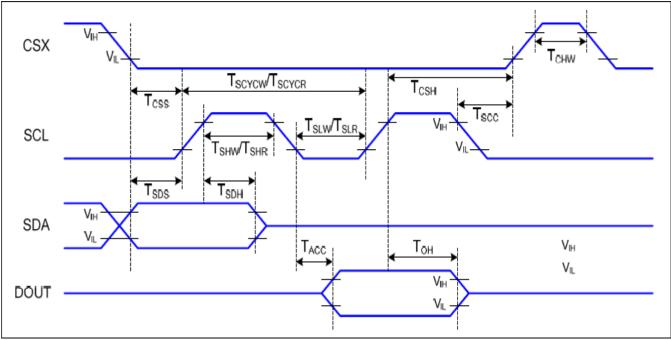


Write to read or read to write timings:

Note: Ta = -30 to 70 C, IOVCC = 1.65V to 2.8V, VCI = 2.6V to 3.3V, GND = 0V.







6.3 Display Serial Interface Characteristics (3-line SPI system)

Figure 6.3: Serial Interface 3-SPI Timing Diagram

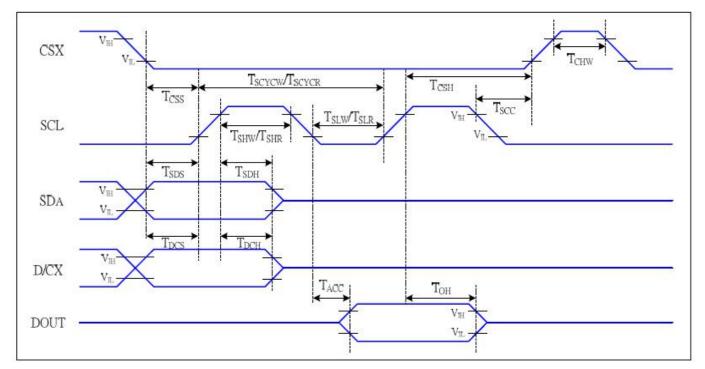
Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (write)	66		ns	
	T _{SHW}	SCL "H" pulse width (write)	15		ns	
SCL	T _{SLW}	SCL "L" width (write)	15		ns	
SCL	T _{SCYCR}	Serial clock cycle (read)	150		ns	
	T _{SHR}	SCL "H" pulse width (read)	60		ns	
	T _{SLR}	SCL "L" pulse width (read)	60		ns	
	T _{SDS}	Data setup time	10		20	
SDA (DIN)	T _{SDH}	Data hold time	10		ns	
	T _{ACC}	Access time	10	50		For max
DOUT	Т _{он}	Output disable time	15	50	ns	CL=30pF For min CL=8pF

VDDI = 1.64 to 3.3V, VDD = 2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 C^o

Table 6.4: 3-line Serial Interface Timing Characteristics

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals





6.4 Display Serial Interface Characteristics (4-line SPI serial)

Figure 6.4: Serial Interface 4-SPI Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (write)	66		ns	write command Q
	T _{SHW}	SCL "H" pulse width (write)	15		ns	write command & data ram
SCI.	T _{SLW}	SCL "L" width (write)	15		ns	uala faili
SCL	T _{SCYCR}	Serial clock cycle (read)	150		ns	read command &
	T _{SHR}	SCL "H" pulse width (read)	60		ns	data ram
	T _{SLR}	SCL "L" pulse width (read)	60		ns	uala faili
	T _{DCS}	D/CX setup time	10		ns	
D/CX	T _{DCH}	D/CX hold time	10		ns	
	T _{SDS}	Data setup time	10		ns	
SDA (DIN)	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For max CL=30pF
DOOT	Т _{ОН}	Output disable time	15	50	ns	For min CL=8pF

Table 6.5: 4-line Serial Interface Timing Characteristics

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



6.5 Reset Timing

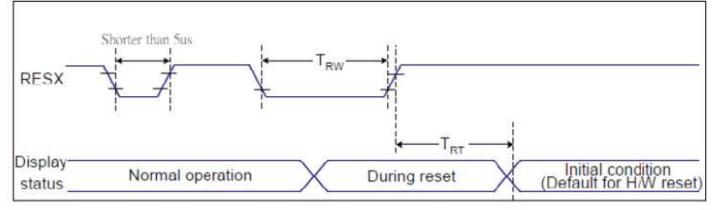


Figure 6.5: Reset Timing Diagram

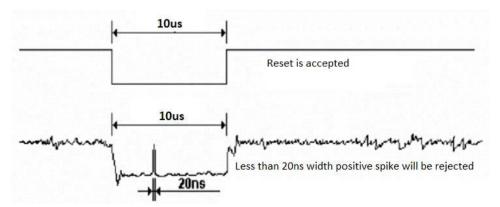
Related Pins	Symbol	Parameter	Min	Max	Unit
	TRW	Reset pulse duration	10	-	us
RESX	тот	Deset series!	-	5 (Note 1,5)	ms
	TRT	Reset cancel		120 (Note 1, 6, 7)	ms

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5ms after a rising edge of RESX.
- 2. Spike due to an electrostatic discharge on RESX line does not because irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9 us	Reset starts

- 3. During the resetting period, the display will be blanked (the display is entering blanking sequence, which maximum time is 120ms, when reset starts in Sleep Out mode. The display remains the blank state in Sleep in mode) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5ms after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120ms.



7. Cautions and Handling Precautions

7.1 Handling and Operating the Module

- 1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
- 2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- 3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- 4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
- 5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- 6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- 7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- 8. Protect the module from static; it may cause damage to the CMOS ICs.
- 9. Use fingerstalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- 10. Do not disassemble the module.
- 11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- 12. Pins of I/F connector shall not be touched directly with bare hands.
- 13. Do not connect, disconnect the module in the "Power ON" condition.
- 14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence.

7.2 Storage and Transportation

- 1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- 2. Do not store the TFT-LCD module in direct sunlight.
- 3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- 4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- 5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.